



DECISION OF THE PUBLIC AUTHORITIES BOARD OF THE ECSEL JOINT UNDERTAKING

Amending the selection of project proposals retained for funding following ECSEL Call 2018-1 and the allocation of funding (decision PAB 2018.38)

THE PUBLIC AUTHORITIES BOARD OF THE ECSEL JOINT UNDERTAKING,

Having regard to the Statutes annexed to Council Regulation (EU) No 561/2014 of 6 May 2014 on the establishment of the ECSEL Joint Undertaking, and in particular Articles 9§5(b) and 12(e);

Having regard to the Decision of the Public Authorities Board on the evaluation and selection procedures related to Calls for proposals¹,

Having regard to the Governing Board decision approving the Work plan for 2018 and describing the scope and budget of ECSEL Calls 2018-1²,

Having regard to decision ECSEL PAB 2018.38 adopting the selection of project proposals retained for funding following ECSEL Call 2018-1 and the allocation of funding;

WHEREAS:

- (1) Since the adoption of decision ECSEL PAB 2018.38, some modifications within project consortia and/or budget allocation have occurred;
- (2) The proposal CPS4EU fulfills the conditions to be lifted from the reserve list to the selected list;
- (3) These changes should be approved by the PAB as Grant Agreements signed between the Joint Undertaking and projects beneficiaries should reflect the decision of the PAB,

¹ ECSEL PAB 2018.31

² ECSEL GB 2018.116

HAS ADOPTED THIS DECISION:

Article 1

Annexes 2, 3 and 5 of decision ECSEL PAB 2018.38 are hereby modified and replaced by the ones provided in Annex.

Article 2

The other provisions of decision ECSEL PAB 2018.38 shall remain valid.

This Decision shall enter into force on the date of its adoption.

Done at Brussels, on 6 May 2019,

For the Public Authorities Board



Ben Ruck

Chairperson of the Public Authorities Board

Annexes:

- Annex 2: list of selected proposals retained for funding
- Annex 3: list of projects on reserve list
- Annex 5: selected proposals: detailed tables – CONFIDENTIAL

ANNEX 2 - LIST OF SELECTED PROPOSALS RETAINED FOR FUNDING**Call: ECSEL 2018-1**

Project	H2020 Cost	EU Contribution	Coordinator	Nationality
APPLAUSE	34,688,348.87	8,587,525.76	ICOS VISION SYSTEMS NV	BE
Arrowhead Tools	90,709,908.53	22,761,457.01	LULEA TEKNISKA UNIVERSITET	SE
CPS4EU	53,019,297.66	12,972,791.56	VALEO VISION	FR
MADEin4	126,176,472.50	29,382,452.28	APPLIED MATERIALS ISRAEL	IL
PIN3S	119,581,291.50	26,787,918.69	ASML NETHERLANDS B.V.	NL
Power2Power	74,257,768.75	16,966,654.96	INFINEON TECHNOLOGIES DRESDEN	DE
VIZTA	87,794,764.25	21,342,431.14	STMICROELECTRONICS CROLLES	FR
Grand Total	586,227,852.06	138,801,231.40		

Project	Participant
APPLAUSE	<p>ICOS VISION SYSTEMS NV, ROODMICROTEC GMBH, NUROMEDIA GMBH, PAC TECH - PACKAGING TECHNOLOGIES GMBH, DISCO HI-TEC EUROPE GMBH, OSYPKA AG, FRAUNHOFER GESELLSCHAFT ZUR FOERDERUNG DER ANGEWANDTEN FORSCHUNG E.V., WUERTH ELEKTRONIK ROT AM SEE GMBH & CO. KG, Besi Netherlands BV, ADVANCED PACKAGING CENTER BV, STICHTING IMEC NEDERLAND, JSR MICRO NV, INTERUNIVERSITAIR MICRO-ELECTRONICA CENTRUM, VAISALA OYJ, GE HEALTHCARE FINLAND OY, AFORE OY, Oy Everon Ab, Precordior Oy, TURUN YLIOPISTO, AALTO KORKEAKOULUSAATIO SR, INTEGRATED DETECTOR ELECTRONICS AS, CARDIACCS AS, UNIVERSITETET I SOROST-NORGE, AMS AG, BESI AUSTRIA GMBH, EV GROUP E. THALLNER GMBH, ALBIS OPTOELECTRONICS AG, CSEM CENTRE SUISSE D'ELECTRONIQUE ET DE MICROTECHNIQUE SA - RECHERCHE ET DEVELOPPEMENT, Almae Technologies, SEMILAB FELVEZETO FIZIKAI LABORATORIUM RESZVENYTARSASAG, DUSTPHOTONICS LTD, ELEKTRONIKAS UN DATORZINATNU INSTITUTS</p>
Arrowhead Tools	<p>LULEA TEKNISKA UNIVERSITET, AEE - INSTITUT FUR NACHHALTIGE TECHNOLOGIEN, ACCIONA CONSTRUCCION SA, ARCELIK A.S., BETTERSOLUTIONS SA, BNEARIT AB, BOLIDEN MINERAL AB, dotGIS corporation, ECLIPSE FOUNDATION EUROPE GMBH, EQUA SIMULATION AB, EUROTECH SPA, FAGOR ARRASATE S COOP, FAGOR AUTOMATION S COOP LTDA, POLITECHNIKA GDANSKA, IKERLAN S COOP, INFINEON TECHNOLOGIES AUSTRIA AG, INFINEON TECHNOLOGIES DRESDEN GMBH & CO KG, INFINEON TECHNOLOGIES AG, USTAV TEORIE INFORMACE A AUTOMATIZACE AV CR VVI, CONSORZIO NAZIONALE INTERUNIVERSITARIO PER LA NANOELETTRONICA, JOTNE EPM TECHNOLOGY AS, KAI KOMPETENZENTRUM AUTOMOBIL - UND INDUSTRIELEKTRONIK GMBH, LINDBACKS BYGG AB, Lundqvist Trävaru AB, MONDRAGON GOI ESKOLA POLITEKNIKOA JOSE MARIA ARIZMENDIARRIETA S COOP, MONDRAGON SISTEMAS DE INFORMACION SOCIEDAD COOPERATIVA, HOGSKOLEN I OSTFOLD, PHILIPS MEDICAL SYSTEMS NEDERLAND BV, PODCOMP AB, POLITECNICO DI TORINO, SANTER REPLY SPA, KNOWLEDGE CENTRIC SOLUTIONS SL, STMICROELECTRONICS SRL, NTNU, TELLU IOT AS, TECHNISCHE UNIVERSITAET DRESDEN, TECHNISCHE UNIVERSITAET KAISERSLAUTERN, UNIVERSIDAD CARLOS III DE MADRID, ULMA EMBEDDED SOLUTIONS S COOP, Kompetenzzentrum - Das Virtuelle Fahrzeug, Forschungsgesellschaft mbH, SIRRIS HET COLLECTIEF CENTRUM VAN DE TECHNOLOGISCHE INDUSTRIE, 3E NV, VOLVO LASTVAGNAR AB, ELEKTRONIKAS UN DATORZINATNU INSTITUTS, FACHHOCHSCHULE BURGENLAND GMBH, VYSOKE UCENI TECHNICKE V BRNE, CESKE VYSOKE UCENI TECHNICKE V PRAZE, ROPARDO SRL, SAP Norway AS, INSTITUTE FUR ENGINEERING DESIGN OF MECHATRONIC SYSTEMS UND MPLM EV, CISC SEMICONDUCTOR GMBH, INSTITUT FUER AUTOMATION UND KOMMUNIKATION E.V. MAGDEBURG, COMMISSARIAT A L ENERGIE ATOMIQUE ET AUX ENERGIES ALTERNATIVES, MAGILLEM DESIGN SERVICES SAS, TECHNEXT, STMICROELECTRONICS GRENOBLE 2 SAS, AITIA INTERNATIONAL INFORMATIKAI ZARTKORUEN MUKODO RT, evopro Innovation Ltd. , BUDAPESTI MUSZAKI ES GAZDASAGTUDOMANYI EGYETEM, INCQUERY LABS KUTATAS-FEJLESZTESI KFT, UNIVERSIDADE NOVA DE LISBOA, UNIVERSITAT ZU LUBECK, BEIA CONSULT INTERNATIONAL SRL, TECHNISCHE UNIVERSITEIT EINDHOVEN, AIT AUSTRIAN INSTITUTE OF TECHNOLOGY GMBH, SYSTEMA SYSTEMENTWICKLUNG DIPL INF.MANFRED AUSTEN GMBH, Semantis Information Builders GmbH, ROBERT BOSCH GMBH, ASML NETHERLANDS B.V., ICT AUTOMATISERING NEDERLAND BV, EQUA Solutions AG, Hochschule fuer Technik und Wirtschaft Dresden, BOSCH SOFTWARE INNOVATIONS GMBH, ASSYSTEM GERMANY GMBH, MONDRAGON CORPORACION COOPERATIVA SCOOP, WAPICE OY, ABB OY, Teknologian tutkimuskeskus VTT Oy, TECHNOLUTION BV, CAMEA, CSC</p>
CPS4EU	<p>VALEO VISION, ACOEM (01dB-Metravib), AIRLANE TECHNOLOGIES, ANSYS FRANCE, ARCURE, CNRS, CEA, EMBEDDED FRANCE, GREENWAVES TECHNOLOGIES, GLOBALSENSING TECHNOLOGIES, INSTITUT NATIONAL DE RECHERCHE EN INFORMATIQUE ET AUTOMATIQUE, CAPTRONIC (JESSICA FRANCE), KALRAY, M3 SYSTEMS, PROVE&RUN, RTE, SCHNEIDER ELECTRIC FRANCE, SEQUANS COMMUNICATIONS, SHERPA ENGINEERING, SYSSNAV, THALES RESEARCH & TECHNOLOGY, UNIVERSITE GRENOBLE ALPES, VSORA, Abengoa Innovación, Tecnologías, Servicios Telemáticos y Sistemas, S.A., Fundación Centro de Tecnologías de Interacción Visual y Comunicaciones, Budapest University of Technology and Economics, Spinsplit Technical Research and Development Limited Liability Company, EUROTECH S.P.A., Leonardo Spa, University of Salerno, ACS plus, emmtrix, Technische Universität Clausthal, TRUMPF Ditzingen, University Augsburg, WIKA Mobile Control GmbH, Instituto Tecnológico de Informática</p>

MADEin4	APPLIED MATERIALS ISRAEL LTD, ARKEMA FRANCE, AVL DITEST GMBH, AVL LIST GMBH, Brillianetor Ltd., BRUKER JV ISRAEL LTD, CENTRE NATIONAL DE LA RECHERCHE SCIENTIFIQUE CNRS, COMAU SPA, COMMISSARIAT A L ENERGIE ATOMIQUE ET AUX ENERGIES ALTERNATIVES, CONSIGLIO NAZIONALE DELLE RICERCHE, ENTEGRIS CLEANING PROCESS (ECP) SAS, EXCILLUM AB, FEI ELECTRON OPTICS BV, FIAT CHRYSLER AUTOMOBILES ITALY SPA, FLEXIBLE OPTICAL BV, GLOBALFOUNDRIES Dresden Module One LLC & Co. KG, ICOS VISION SYSTEMS NV, INSTITUT MINES-TELECOM, ICT Integrated Circuit Testing GmbH, INTERUNIVERSITAIR MICRO-ELECTRONICA CENTRUM, Ippon Innovation, KLA-TENCOR CORPORATION (ISRAEL), Kompetenzzentrum - Das Virtuelle Fahrzeug, Forschungsgesellschaft mbH, MELLANOX TECHNOLOGIES LTD - MLNX, MENTOR GRAPHICS DEVELOPMENT CROLLES SARL, NANOMOTION LTD, Nearfield Instruments B.V., NEDERLANDSE ORGANISATIE VOOR TOEGEPAST NATUURWETENSCHAPPELIJK ONDERZOEK TNO, NOVA MEASURING INSTRUMENTS LTD, OCTO Technology, PFEIFFER VACUUM, PHYSIKALISCH-TECHNISCHE BUNDESANSTALT, POLITECNICO DI TORINO, PRODRIVE TECHNOLOGIES BV, PVA TEPLA ANALYTICAL SYSTEMS GMBH, SEMI Europe GmbH, SEMILAB FELVEZETO FIZIKAI LABORATORIUM RESZVENYTARSASAG, STMICROELECTRONICS CROLLES 2 SAS, STMICROELECTRONICS ROUSSET SAS, STMICROELECTRONICS SRL, TECHNISCHE UNIVERSITEIT DELFT, TECHNISCHE UNIVERSITEIT EINDHOVEN, THERMO FISHER SCIENTIFIC (BREMEN) GMBH, TOWER SEMICONDUCTOR LTD, UNIVERSITE D'AIX MARSEILLE, UNITY SEMICONDUCTOR, UNIVERSITATEA POLITEHNICA DIN BUCURESTI
PIN3S	ASML NETHERLANDS B.V., APPLIED MATERIALS BELGIUM, APPLIED MATERIALS ISRAEL LTD, Berliner Glas KGaA Herbert Kubatz GmbH & Co., SIOUX CCM BV, COVENTOR SARL, FRAUNHOFER GESELLSCHAFT ZUR FOERDERUNG DER ANGEWANDTEN FORSCHUNG E.V., ION BEAM SERVICES, INTERUNIVERSITAIR MICRO-ELECTRONICA CENTRUM, KLA-Tencor MIE GmbH, KLA-TENCOR CORPORATION (ISRAEL), NOVA MEASURING INSTRUMENTS LTD, PFEIFFER VACUUM, PRODRIVE TECHNOLOGIES BV, RECIF TECHNOLOGIES, REDEN B.V., SCIA SYSTEMS GMBH, SOLMATES BV, FEI ELECTRON OPTICS BV, TECHNISCHE UNIVERSITEIT DELFT, UNIVERSITEIT TWENTE, UNIVERSITATEA POLITEHNICA DIN BUCURESTI, VDL ETG TECHNOLOGY & DEVELOPMENT BV, CARL ZEISS SMT GMBH
Power2Power	INFINEON TECHNOLOGIES DRESDEN GMBH& CO KG, AVL SOFTWARE AND FUNCTIONS GMBH, ELEKTRISCHE AUTOMATISIERUNGS- UND ANTRIEBSTECHNIK EAAT GMBH CHEMNITZ, FRAUNHOFER GESELLSCHAFT ZUR FOERDERUNG DER ANGEWANDTEN FORSCHUNG E.V., HESSE GMBH, HOCHSCHULE ZITTAU-GORLITZ, INFINEON TECHNOLOGIES AG, mi2-factory GmbH, SGS Institut Fresenius GmbH, SILTRONIC AG, TECHNISCHE UNIVERSITAET CHEMNITZ, TECHNISCHE UNIVERSITAET DRESDEN, TECHNISCHE UNIVERSITAET ILMENAU, UNIVERSITAET BREMEN, UNIVERSITAET PADERBORN, UNIVERSITAET ROSTOCK, X-FAB Dresden GmbH & Co. KG, X-FAB SEMICONDUCTOR FOUNDRIES AG, CTR CARINTHIAN TECH RESEARCH AG, INFINEON TECHNOLOGIES AUSTRIA AG, Kompetenzzentrum - Das Virtuelle Fahrzeug, Forschungsgesellschaft mbH, MATERIALS CENTER LEOBEN FORSCHUNG GMBH, BRUSA ELEKTRONIK AG, EIDGENOESSISCHE TECHNISCHE HOCHSCHULE ZUERICH, AGENCIA ESTATAL CONSEJO SUPERIOR DE INVESTIGACIONES CIENTIFICAS, FAGOR AUTOMATION S COOP LTDA, INGTEAM POWER TECHNOLOGY SA, TECNOLOGIAS SERVICIOS TELEMATICOS Y SISTEMAS S.A., UNIVERSIDAD DE OVIEDO, UNIVERSIDAD POLITECNICA DE MADRID, AALTO KORKEAKOULUSAATIO SR, ABB OY, Kemppi Oy, Powernet Oy, INFINEON TECHNOLOGIES CEGLED TELJESITMENYFELVEZETOKET GYARTO KORLATOLT FELELOSSEGU TARSASAG, POWERTEC SRO, SLOVENSKA TECHNICKA UNIVERZITA V BRATISLAVE, ADVANCED PACKAGING CENTER BV, alfen bv, BOSCHMAN TECHNOLOGIES BV, IWO Project b.v., JIACO Instruments BV, TECHNISCHE UNIVERSITEIT DELFT
VIZTA	STMICROELECTRONICS CROLLES 2 SAS, STMICROELECTRONICS GRENOBLE 2 SAS, COMMISSARIAT A L ENERGIE ATOMIQUE ET AUX ENERGIES ALTERNATIVES, III-V LAB, VEONEER SWEDEN AB, INTEGRATED SYSTEMS DEVELOPMENT S.A., Beamagine S.L, IDEMIA IDENTITY & SECURITY FRANCE, STMICROELECTRONICS SA, STMICROELECTRONICS (RESEARCH & DEVELOPMENT) LTD, IBEO AUTOMOTIVE SYSTEMS GMBH, IEE INTERNATIONAL ELECTRONICS & ENGINEERING SA, LUMIBIRD, ELEKTRONIKAS UN DATORZINATNU INSTITUTS, DEUTSCHES FORSCHUNGSZENTRUM FUR KUNSTLICHE INTELLIGENZ GMBH, SEMILAB FELVEZETO FIZIKAI LABORATORIUM RESZVENYTARSASAG, APPLIED MATERIALS FRANCE, Philips Photonics GmbH, UNIVERSITAT POLITECNICA DE CATALUNYA, FUNDACIO EURECAT, FICOMIRRORS SA, ALTER TECHNOLOGY TUV NORD SA, BCB Informatica y Control S.L.

ANNEX 3 - LIST OF PROPOSALS RETAINED FOR THE RESERVE LIST

No proposal on the reserve list.